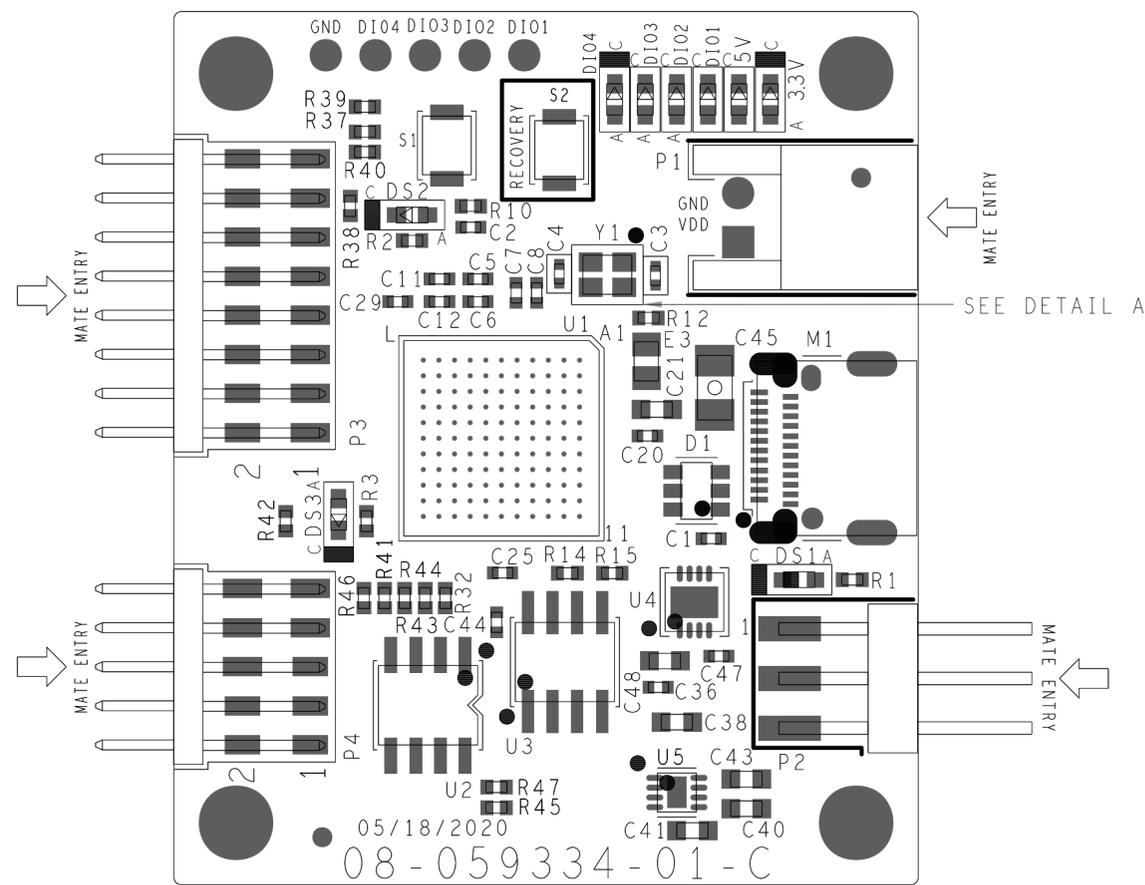
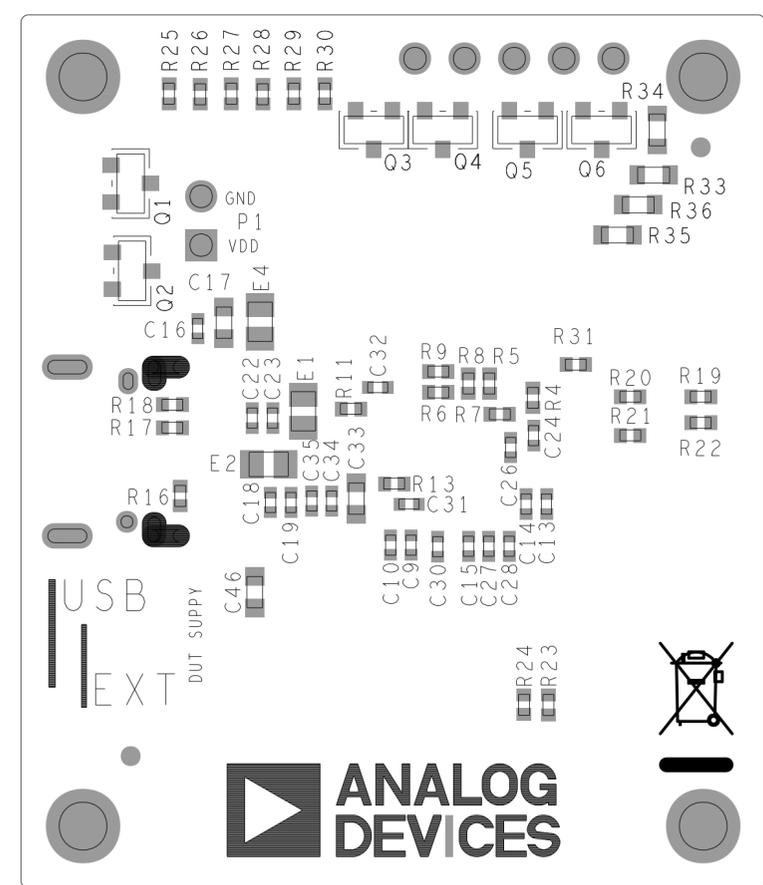


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE: NHR-059241	12/6/19	J. CHONG
B	ECR-093672	18MAR20	J. CHONG
C	ECR-095003	18MAY20	J. CHONG

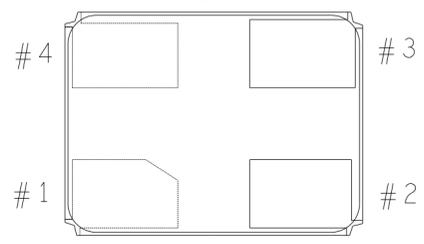


TOP ASSEMBLY



BOTTOM ASSEMBLY

Note: Actual device pin #1 has a chamfered corner terminal as shown.



YSML98W79H26
NX2520SA-19.200000MHZ-NBG1
DETAIL A

GENERAL ASSEMBLY NOTES:

1. THE PRINTED CIRCUIT BOARD SHALL BE ASSEMBLED USING INDUSTRY STANDARD BEST PRACTICES PER IPC-A 610 CLASS 2.
2. THE PRINTED CIRCUIT BOARD SHALL BE ASSEMBLED IN COMPLIANCE WITH ROHS STANDARDS FOR LEAD FREE PRODUCTS. RECOMMENDED SOLDER COMPOSITION IS 96.5 SN / 3 AG / 0.5 CU OR EQUIVALENT.
3. THE PRINTED CIRCUIT BOARD ASSEMBLY SHALL BE CAPABLE OF STORAGE AT TEMPERATURES FORM -55* TO 150*.
4. FLUX SHALL BE USED FOR ALL SOLDERING, WATER SOLUBLE ORGANIC ACID FLUX.
5. THE FINAL ASSEMBLY SHALL BE FREE OF FLUX RESIDUE AND FOREIGN MATERIAL AND (20.00 UG/SO INCH NACL EQUIVALENT).
6. TWO PART ADHESIVE SHALL BE USED UNDER USB CONNECTOR FOR REPITIVE CONNECTION FORCE ABSOBTION.
7. A CERTIFICATE OF COMPLIANCE SHALL BE SENT WITH EACH ASSEMBLY LOT.
8. SEE DETAIL A FOR Y1 PIN1 ORIENTATION.
9. RoHS COMPLIANCE: ASSEMBLY VENDOR SHOULD ASSURE COMPLIANCE WITH LEAD-FREE AND RoHS PCB ASSEMBLY STANDARDS (EU RoHS DIRECTIVE 2002/95/EC).

PRIMARY SIDE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMALS FRACTIONS ANGLES .XX -.010 --1/32 -- 2 .XXX -.005 .XXXX -.0050	APPROVAL	DATE	WWM DIVISION 804 WOBURN STREET WILMINGTON, MA 01887				
	TEMPLATE ENGINEER						
	HARDWARE SERVICES		TITLE ASSEMBLY FX3-ISENSOR-POD CUSTOMER EVALUATION Z				
	HARDWARE SYSTEMS						
MATERIAL	TEST ENGINEER						
FINISH	COMPONENT ENGINEER		SIZE	FSCM NO	DRAWING NUMBER	REV	
	TEST PROCESS						
	HARDWARE RELEASE		PTD ENGINEER J. CHONG CHECKER	06DEC19	C	34031	01-059334-01
DO NOT SCALE DWG			SCALE	1/1		SHEET 1 OF 1	